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(54) **DUAL-STACKED MOTHERBOARDS FOR FLUID IMMERSION COOLING**

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(57) **ABSTRACT**

A server computer system has one or more node assemblies. A node assembly has two motherboards that are stacked one over another with their component sides facing toward each other. Memory cards that are mounted on one motherboard are interlaced with memory cards that are mounted on the other motherboard. At least processors of the two motherboards are immersed in a coolant fluid in a fluid immersion cooling tank. A processor cooling stack is mounted over a processor. The processor cooling stack includes flow regulation structures with sidewalls that regulate flow of vapor bubbles of the coolant fluid away from the processor.